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Awards & Recognition

A highlight of ECTC has always been the CPMT lunch where IEEE and CPMT recognized exceptional individuals in our midst for their major and significant contributions to our profession and our society. I had the honor to present the IEEE CPMT Field Award to Dimitry Grabbe for his many contributions to advanced printed circuit board technology and connector technology in a professional career of over a half century. I was also privileged to share the podium with Dr Kitty Pearsall, CPMT Strategic Director for Awards and Recognition, to present this year's CPMT Society Awards for contributions and achievements. The list of award recipients and corresponding citations appear elsewhere in this newsletter. Last but not least, we recognized those members in our midst who have attained the highest membership level as an IEEE Fellow this year. The award winners and Fellows comprise a group of extraordinary professionals. Each in his/her own way has contributed much to our profession. And it is important that we recognize our own in major CPMT conferences, including ECTC, EPTC, ESTC, EMAP, IEMT and many others.

Winds of Change

If one should ask me, what were the over-riding impressions that I carry with from ECTC 2007, I would say they are the accelerating pace of technology change, and perhaps equally important, an expanding mindset welcoming change among the participants. The winds of change are gale winds blowing strong.

The traditional perspective of the roles of the packaging engineer is (a) make electrical interconnects and maintain off-chip signal integrity, (b) keep the IC and package temperature in check, (c) keep the IC and package from breaking down over its service life. Moore's Law drives the industry front-end for timed invention, innovation and their implementation. With the waves of SiP, wafer level packaging and 3D packaging technologies coming to the front, the roles of packaging engineers are taking on new dimensions. On the one hand the advancements of WLP and TSV are breaking down the walls between the foundry and packaging. On the other hand the forces unleashed by SiP technologies lead directly to system integration and electronic product realization. In this world of electronics industry the walls between the supply chains are fast vanishing. Are we ready for the challenges and opportunities presented by the advancing and sometimes disruptive technologies and evolving industry business model.

A Safe Harbor

In this fast-changing world of shifting opportunities, the global IEEE/CPMT community is becoming a safe harbor for relevant knowledge, technology innovations, life-long education, global networking, and peer recognition. I would like to invite you to participate in other CPMT conferences and workshops in different regions world-wide. There is still time for abstract submissions and technical exhibitions. They are great opportunities for technical vitality and building your personal networking within those regions. At the Board of Governors workshop last week we asked the Regional Strategic Directors to co-ordinate participation from

publications, technical committees and membership at CPMT related conferences and workshops. I am confident that they will be working enthusiastically towards those ends.

Do go to the CPMT Web Page to see which technical conferences are of professional interest. Check out the Transactions for the latest developments in your field. Volunteer to be a speaker at your local chapter meeting. The Transactions editors would welcome your contributions as authors and reviewers. Tell your colleagues about CPMT and invite them to join.

A vital global CPMT Society is of benefit to everyone, especially today.

CPMT Society News:

IEEE Components, Packaging and Manufacturing Technology Society Board of Governors Meeting June 1st – 2nd, 2007 Reno, Nevada, USA

Report

Submitted by Ms. Marsha Tickman, Executive Director, IEEE CPMT Society

The IEEE CPMT Society Board of Governors held its first meeting of 2007 on 1st and 2nd June 2007 in Reno, Nevada, USA, following the 57th ECTC.

The meeting began on Friday evening, 1 June 2007, with the third in a series of workshops allowing for informal discussion on strategic issues. This workshop continued discussion on creating global communities to serve members of our profession – and methods and strategies to achieve this. Topics included: defining the CPMT Society value propositions, breaking down silos within Society activities and building linkages, creating/utilizing a Regional organization.

On Saturday 2 June 2007, the Board of Governors meeting was called to order at 8:30 am. The following actions were taken:

- Approved minutes of the November 2006 Board of Governors meeting.
- Ratified actions approved via e-mail ballot between the November 2006 and current Board of Governors meetings.
- Approved employing additional staff to support the Transactions Editors and improve review process cycle time.
- Approved change in cosponsorship for the International Electronics Manufacturing Technology Symposium (IEMT): 50% CPMT Santa Clara Valley Chapter; 50% CPMT Society.
- Approved change in cosponsorship for the Organic Microelectronics Workshop: 25 % American Chemical Society, 25% Materials Research Society, 25% American Physical Society, 12.5% Solid-State Circuits Society (IEEE), 12.5% CPMT.
- Approved change in cosponsorship for the International Symposium on Advanced Packaging Materials: Processes, Properties and Interfaces (APM'07): 50% CPMT Santa Clara Valley Chapter; 50% CPMT Society.
- Approved new 100% Sponsorship of the International Workshop on Advances in Sensors and Interfaces (IWASI).
- Approved new Technical Cosponsorship w/fee of the 2007 Workshop on 3D Integration.

- Approved new Graduate Fellowship of \$10K with \$5K travel support to begin in 2008; modeled after the Motorola/IEEE CPMT Graduate Fellowship.
- Approved Johan Liu as a CPMT Distinguished Lecturer.
- Approved George Harman as a CPMT Distinguished Lecturer.
- Approved appointment of Eric Beyne as Strategic Director, Region 8.

Reports were presented as follows:

- CPMT President's Vision for CPMT Society
- Finances
- Publications
- Transactions
- Conferences
- Region 10 Activities
- ECTC Integration/57th ECTC
- Education
- Nominations
- Fellows Evaluation
- Fellows Search
- Constitution and Bylaws
- Technical Programs
- Region 8 Programs
- Membership and Chapters
- Student Programs
- Awards and Recognition
- Marketing

The next meeting of the CPMT Board of Governors is scheduled for 9-10 November 2007 following the ECTC Paper Selection Meeting, Dallas, TX, USA.

The meeting was adjourned at 4:30 pm.

Board of Governors Workshop Summary

Submitted by Dr. Dave Palmer, IEEE Fellow, Sandia National Laboratories

CPMT President William Chen held the third workshop for the Society Board of Governors on Friday, 1st June 2007, evening in Reno right after the ECTC. A few "new" members were introduced: Petri Savolainen, Kitty Pearsall, Paul Franzon, Eric Beyne, and Philip Chan.

The President quickly reviewed the results of the first workshop where each of the thrusts of our Society (publications, conferences, technical committees, education programs, chapter and membership development, and awards and recognition) were reviewed with the "value proposition" perspective to see how to enhance the impact for our members and our profession.

The second workshop addressed the Society's efforts at Globalization to serve the more geographically dispersed members. A few potential chapter areas (high member density) have been chosen to concentrate our effort: Ottawa, Austin, Germany, Norway, Japan, Malaysia, and Korea.

Much discussion was on the attempt not to let the good work of various parts of the Society to be limited within their own Silo (stovepipe). For example, the great organization of ECTC does feed into Chapter development, publications

(best papers are fed into the Transactions input), technical committee growth (TCs meet at breakfast meetings), and awards (given at luncheons). However not all of our activities are this synergistic.

Several topics were discussed in some detail including publications enhancements such as shortening time to print and eliminating laggard manuscripts. Linking publications to specific conferences and expanding our stakeholders by adding authors, editors, and reviewers for the Transactions were examples of using publications as a catalyst for the Society.

Dimitry Grabbe Presented IEEE Technical Field Award for Components, Packaging and Manufacturing Technology

Submitted by Ms. Jacquelyn Hampton, Potomac Communications Group

- *Dimitry Grabbe awarded IEEE Technical Field Award for Components Packaging and Manufacturing Technology - Award is one of the highest honors conferred by the IEEE*
- *Grabbe's contributions have played an integral part in advancing U.S. space exploration*

PISCATAWAY, N.J., June 14, 2007 - Dimitry Grabbe was presented the IEEE Technical Field Award for Components, Packaging and Manufacturing Technology on May 31 during the 57th Electronic Components and Technology Conference in Reno, Nev. USA.



Grabbe was recognized for his contributions to the fields of electrical/electronic connector technology and development of multi-layer wiring boards. The award is part of the Technical Field Awards program and is sponsored by the IEEE Components, Packaging and Manufacturing Technology Society. It recognizes commendable contributions to the advancement

of components, electronic packaging or manufacturing technologies.

"There are very few engineers who have made as many contributions to advancing electronic and optoelectronic connectors and associated technologies," said Grabbe's peer who nominated him for the award. "For the last fifty years, Dimitry has been a leader in creating new products and new manufacturing approaches that have accounted for many significant improvements."

Dr. William T. Chen, President of the IEEE CPMT Society noted, "Mr. Grabbe is a brilliant individual whose efforts in electrical/electronic connector technology and the development of multi-layer wiring boards has contributed to major advancements in this industry."

Grabbe currently assists in research on gyroscopes and accelerometers with Dr. Pryputniewicz, professor of mechanical engineering and founding director of the Center for Holographic Studies and laser micro-mechanics at Worcester Polytechnic Institute in Mass.

Highlights from Grabbe's career:

- Pioneered work that has produced nearly 500 U.S. and foreign patents covering machine design, semiconductor packaging, electronics assembly and optoelectronic conductor design.